


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/21/12623	
1.3 Title of PCN	STM32WLxx products enhancement	
1.4 Product Category	STM32WL 256K	
1.5 Issue date	2021-07-16	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRAUSE INA
2.1.2 Phone	+49 89460062370
2.1.3 Email	ina.krause@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC Fab14 (Taiwan)

4. Description of change

	Old	New
4.1 Description	<p>STM32WLxxx Devices Cut 1.1 (Version Z) is in production with some limitations as documented in :</p> <p>STM32WL55xx, STM32WL54xx current version - ES0500 - Rev 2 - April 2021 (Errata Sheet) - DS13293 - Rev 1 - November 2020 (Datasheet) - RM0453 - Rev 1 - November 2020 (Reference Manual)</p> <p>STM32WLE5xx, STM32WLE4xx current version - ES0506 - Rev 2 - April 2021 (Errata Sheet) - DS13105 - Rev 8 - November 2020 (Datasheet) - RM0461 - Rev 3 - November 2020 (Reference Manual)</p>	<p>STM32WLxxx Cut 1.2 (Version Y) Devices introduces new features (long-packet) and feature enhancements as documented in :</p> <p>STM32WL55xx, STM32WL54xx new documentations - ES0500 - Rev 3 - June 2021 (Errata Sheet) - DS13293 - Rev 2 - June 2021 (Datasheet) - RM0453 - Rev 2 - June 2021 (Reference Manual)</p> <p>STM32WLE5xx, STM32WLE4xx new documentations - ES0506 - Rev 3 - June 2021 (Errata Sheet) - DS13105 - Rev 9 - June 2021 (Datasheet) - RM0461 - Rev 4 - June 2021 (Reference Manual)</p>
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Impact on Function: improvements as indicated in documents listed. Remains fully compatible with existing Embedded Software	

5. Reason / motivation for change

5.1 Motivation	STM32WL Cut 1.2 (Version Y) new feature introduction (long-packet) versus Cut 1.1 (version Z).
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensure by ST internal tools. The die revision changes from "Z" to "Y" is displayed on Marking visible on top side of customer product package.
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7. Timing / schedule

7.1 Date of qualification results	2021-02-05
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7.2 Intended start of delivery	2021-05-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
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8.1 Description	12623 MDG MCD RER1813 V1.3 STM32WL 256K Die 497XXXY Reliability Evaluation Report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2021-07-16

9. Attachments (additional documentations)			
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12623 Public product.pdf 12623 MDG MCD RER1813 V1.3 STM32WL 256K Die 497XXXY Reliability Evaluation Report.pdf 12623 PCN12623_Additional information.pdf
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10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
3515808	STM32WLE5J8I6	
3515809	STM32WLE5JB16	
3515810	STM32WLE5JC16	

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